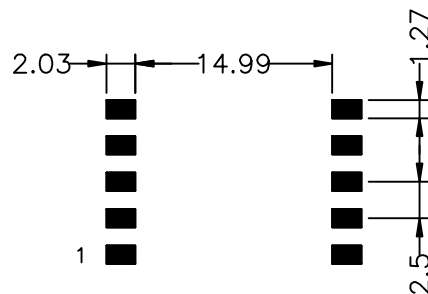


DOT PIN#1

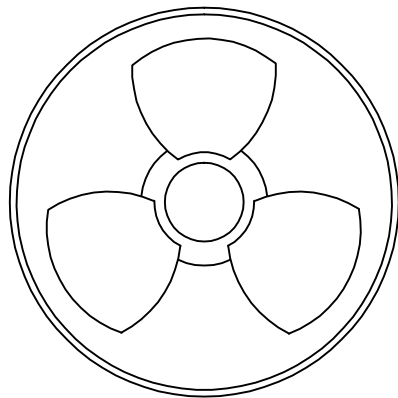
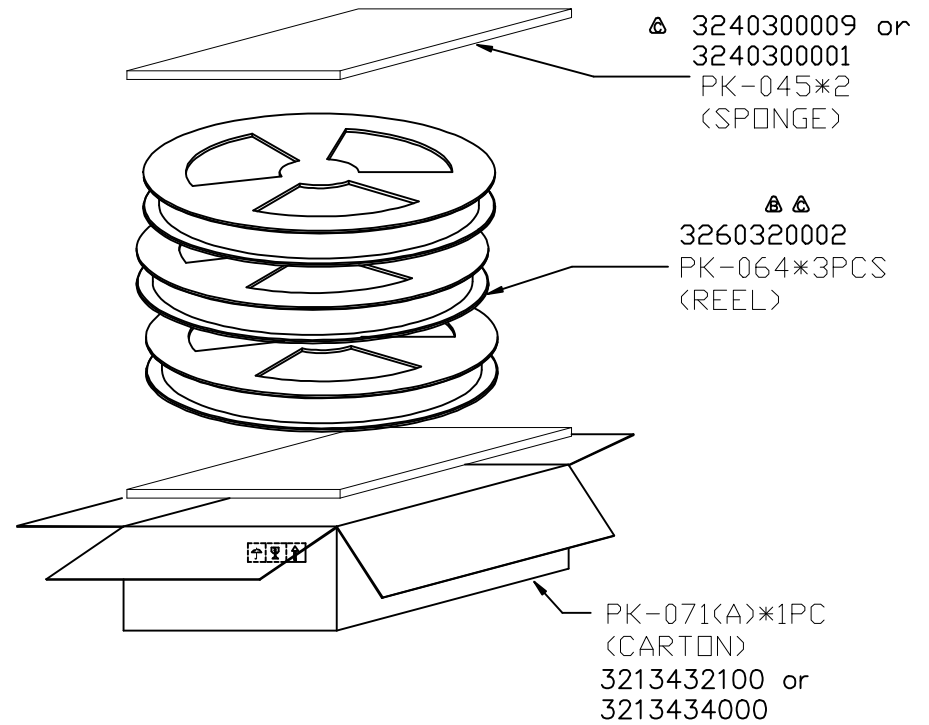
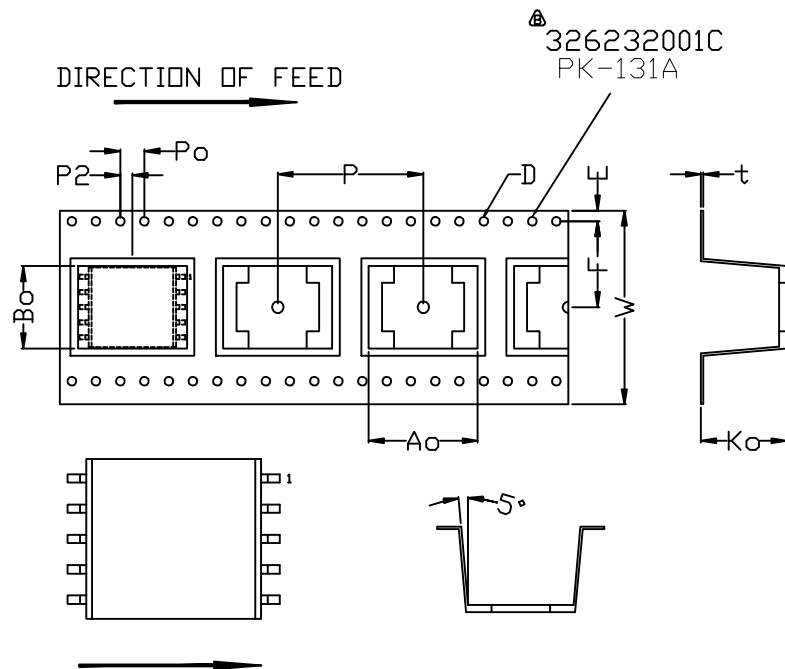


SUGGESTED P.C.B LAYOUT

ELECTRICAL CHARACTERISTICS :

- DCR : 1-10 = 135mΩ MAX.
2-9 = 280mΩ MAX.
4-7 = 75mΩ MAX.
5-6 = 65mΩ MAX.
- INDUCTANCE : (@200KHz, 0.1Vrms) 1-10 : 45uH ±10%
- TURN RATIO : (@100KHz, 0.1Vrms) 1-10 : 5-6 = 3 ±3%
1-10 : 4-7 = 3 ±3%
1-10 : 2-9 = 2.625 ±3%
- HI-POT : (@1500VAC, 1mA, 2SEC) 1-5 , 1-4
(@500Vrms, 1mA, 2SEC) 1-2
- RoHS COMPLIANT

| | | | | | | | | |
|-----------|-----------------------------------|-------------|---------|-------|-------|----------|--------------|-------------|
| | | | | | | TITLE | | TRANSFORMER |
| B | CHANGE PRINT | 01/21/2020 | SHIRLEY | BETTY | BETTY | AOEM. | | DWG. NO. |
| A | CHANGE ELECTRICAL CHARACTERISTICS | 12/12/2013 | SHIRLEY | BETTY | BETTY | | | ATS-1259R |
| RELEASE | | 8/20/2013 | SHIRLEY | BETTY | BETTY | UNITS: | SAFETY | |
| NO: | | DESCRIPTION | DATE | BY | CHK | APPD | SHEET 1 of 1 | |
| REVISIONS | | | | | | DATE | P/N: | DRAW |
| | | | | | | 08/20/13 | | SHIRLEY |



REEL

每捲放乾燥包1pcs 用真空袋抽真空封口
2780000000 Δ 3255048421 or 3255048420

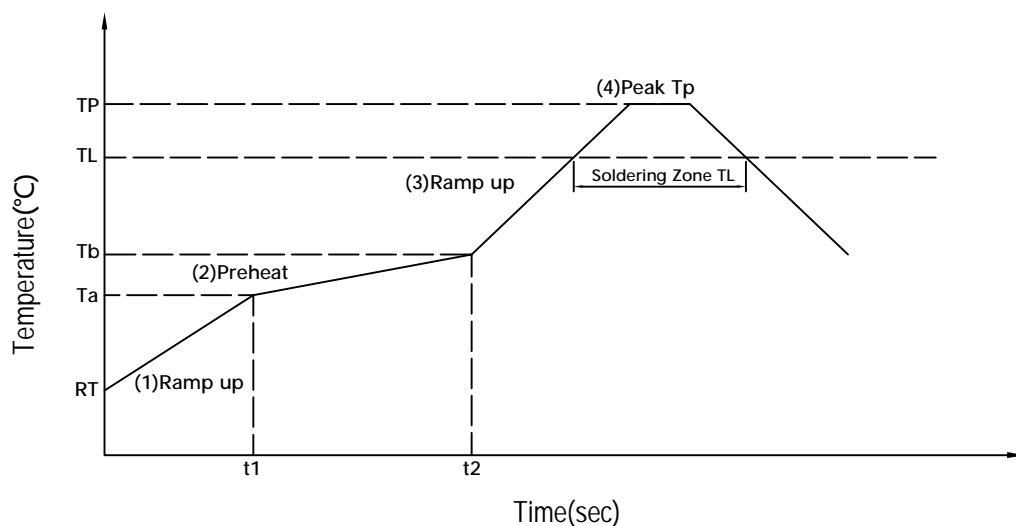
| ITEM | W | Ao | Bo | Ko | P | F | E | D | D1 | Po | P2 | t |
|------|---|---|---|---|---|---|--|--|--|--|--|--|
| DIM | 32.00 ^{+0.30} _{-0.30} | 18.00 ^{+0.10} _{-0.10} | 13.60 ^{+0.10} _{-0.10} | 14.10 ^{+0.10} _{-0.10} | 24.00 ^{+0.10} _{-0.10} | 14.20 ^{+0.10} _{-0.10} | 1.75 ^{+0.10} _{-0.10} | 1.50 ^{+0.10} _{-0.00} | 2.00 ^{+0.25} _{-0.00} | 4.00 ^{+0.10} _{-0.10} | 2.00 ^{+0.10} _{-0.10} | 0.40 ^{+0.05} _{-0.05} |

ONE REEL 200 PCS
ONE CARTON 3 REEL (600 PCS)

| | | | | | | | | | | |
|-----------|------------------|------------|---------|------|--------|--|----------|--|--------------|--|
| C | CHANGE PART NO. | 03/06/2012 | SHIRLEY | JOAN | JOAN | | TITLE | | PACKING | |
| B | CHANGE PART NO. | 03/11/2011 | SHIRLEY | DICK | DICK | | DWG. NO. | | 968TS71800 | |
| A | ADD SPONG&CARTON | 10/04/2005 | BART | PAIR | SUEDY | | UNITS: | | SAFETY | |
| | RELEASE | 04/13/2006 | PAIR | AL | EUGENE | | M/M | | | |
| ND | DESCRIPTION | DATE | BY | CHK | APPD | | DATE | | SHEET 1 OF 1 | |
| REVISIONS | | | | | | | 04/13/06 | | DRAW | |
| | | | | | | | | | Pair | |



Pb-free Soldering IR Reflow(SMD)



- 1,MSL Grade: 1 Level 2,Floor life: 2years 3,Condition:≤30°C RH 85%
2,Form-1(Reference JEDEC J-STD-020D Table 5-2)

| IR reflow profile | | Pb-free |
|--------------------------|--|---------------------|
| step# | Profile Feature | Condition/Duration |
| step1 | Ramp-up rate | 3°C/second max |
| step2 | Preheat:150°C-200°C(Ta-Tb) | t1-t2:60-120seconds |
| step3 | Ramp-up rate(TL to Tp) | 3°C/second max |
| | Temperature maintained above 217°C | 60-150seconds |
| step4 | Peak temperature(Tp) | 260+0/-5°C |
| | Time within 5°C of actual peak temperature | 30seconds max |
| Ramp-down rate(Tp to TL) | | 6°C/second max |

- 3,Form-2(Reference JEDEC J-STD-020D Table 4-2)

| Package Thickness | Volume mm ³ <350 | Volume mm ³ 350-2000 | Volume mm ³ >2000 |
|-------------------|--------------------------------|------------------------------------|---------------------------------|
| <1.6mm | 260+0/-5°C | 260+0/-5°C | 260+0/-5°C |
| 1.6mm-2.5mm | 260+0/-5°C | 250+0/-5°C | 245+0/-5°C |
| >2.5mm | 250+0/-5°C | 245+0/-5°C | 245+0/-5°C |